

2A, 200V - 1000V Fast Recovery Surface Mount Rectifier

FEATURES

- Glass passivated chip junction
- Low power loss, high efficiency
- Fast switching for high efficiency
- Low profile package
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- DC to DC converter
- Switching mode converters and inverters
- General purpose

MECHANICAL DATA

• Case: SOD-128

Molding compound meets UL 94V-0 flammability rating

• Terminal: Matte tin plated leads, solderable per J-STD-002

• Meet JESD 201 class 2 whisker test • Polarity: Indicated by cathode band

• Weight: 0.027g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
l _F	2	Α	
V_{RRM}	200 - 1000	V	
I _{FSM}	50	Α	
T _{J MAX}	150	°C	
Package	SOD-128		
Configuration	Single die		









SOD-128



PARAMETER		SYMBOL	RS2DFS	RS2GFS	RS2JFS	RS2KFS	RS2MFS	UNIT
Marking code on the device	ce		RS2DFS	RS2GFS	RS2JFS	RS2KFS	RS2MFS	
Repetitive peak reverse voltage		V_{RRM}	200	400	600	800	1000	V
Reverse voltage, total rms value		$V_{R(RMS)}$	140	280	420	560	700	V
Forward current		I _F	2					Α
Surge peak forward current, single half sine-	t = 8.3ms				50			А
wave superimposed on rated load	t = 1.0ms	140			Α			
Junction temperature		T_J	T _J -55 to +150			°C		
Storage temperature		T _{STG}	-55 to +150			°C		

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THERMAL PERFORMANCE				
PARAMETER	SYMBOL	TYP	UNIT	
Junction-to-lead thermal resistance	$R_{\Theta JL}$	16	°C/W	
Junction-to-ambient thermal resistance	R _{eJA}	73	°C/W	
Junction-to-case thermal resistance	R _{eJC}	14	°C/W	

Thermal Performance Note: Units mounted on PCB (5mm x 5mm Cu pad test board)

PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
		I _F = 1.0A, T _J = 25°C		0.93	-	V
	RS2DFS	I _F = 2.0A, T _J = 25°C		1.01	1.30	V
	RS2GFS RS2JFS	I _F = 1.0A, T _J = 125°C		0.78	-	V
Forward voltage (1)		I _F = 2.0A, T _J = 125°C		0.88	1.02	V
Forward voltage ⁽¹⁾		$I_F = 1.0A, T_J = 25^{\circ}C$	V _F	0.98	-	V
	RS2KFS	I _F = 2.0A, T _J = 25°C		1.06	1.30	V
	RS2MFS	I _F = 1.0A, T _J = 125°C		0.83	-	V
		I _F = 2.0A, T _J = 125°C		0.93	1.05	V
Reverse current @ rated V _R ⁽²⁾		T _J = 25°C	1	-	1	μΑ
		T _J = 125°C	– I _R	-	40	μΑ
RS2 RS2				-	150	ns
Reverse recovery time	RS2JFS	$I_F = 0.5A, I_R = 1.0A,$ $I_{rr} = 0.25A$	t _{rr}	-	250	ns
	RS2KFS RS2MFS			-	500	ns
Junction capacitance	RS2DFS RS2GFS RS2JFS	1MHz, V _R = 4.0V	C _J	11	-	pF
·	RS2KFS RS2MFS			10	-	pF

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION			
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING	
RS2xFS	SOD-128	14,000 / Tape & Reel	

Notes:

1. "x" defines voltage from 200V(RS2DFS) to 1000V(RS2MFS)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

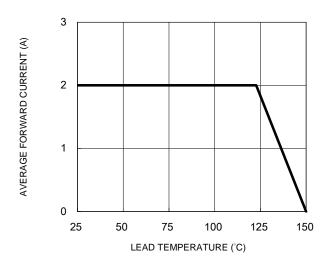


Fig.3 Typical Reverse Characteristics

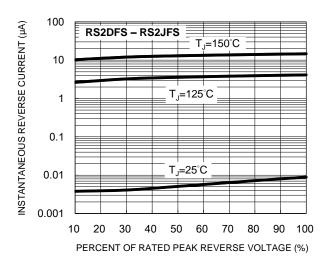


Fig.5 Typical Reverse Characteristics

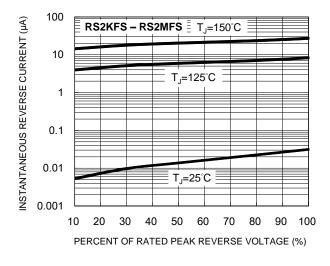


Fig.2 Typical Junction Capacitance

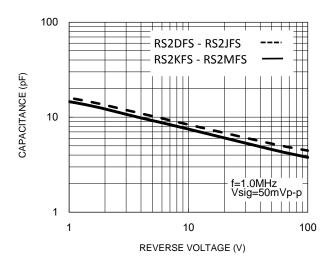


Fig.4 Typical Forward Characteristics

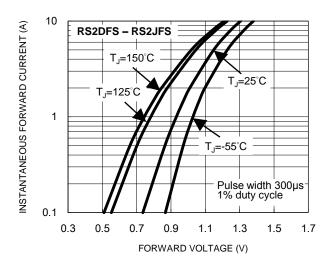
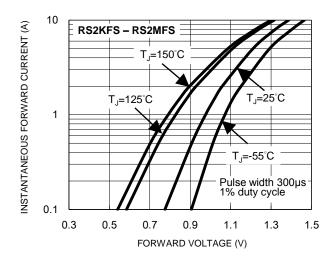


Fig.6 Typical Forward Characteristics

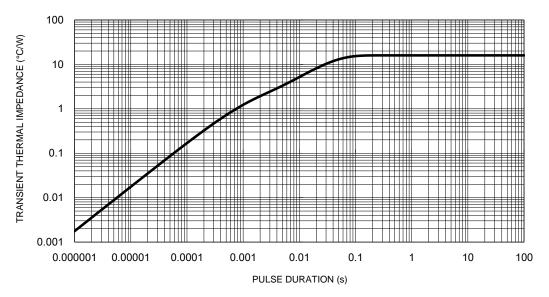




CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

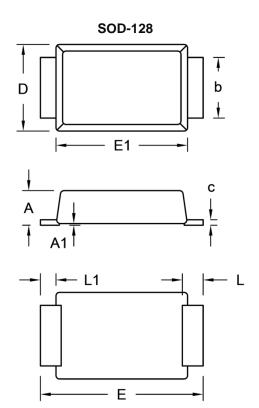
Fig.7 Typical Transient Thermal Impedance





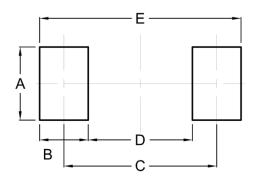
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PACKAGE OUTLINE DIMENSIONS



DIM.	Unit (mm)		Unit ((inch)	
Dilvi.	Min.	Max.	Min.	Max.	
Α	0.90	1.10	0.035	0.043	
A1	0.00	0.10	0.000	0.004	
b	1.60	1.90	0.063	0.075	
С	0.10	0.22	0.004	0.009	
D	2.30	2.70	0.091	0.106	
E	4.40	5.00	0.173	0.197	
E1	3.60	4.00	0.142	0.157	
L	0.40	0.80	0.016	0.031	
L1	0.30	0.60	0.012	0.024	

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
Α	2.10	0.083
В	1.40	0.055
С	4.40	0.173
D	3.00	0.118
E	5.80	0.228

MARKING DIAGRAM



P/N = Marking Code YW = Date Code F = Factory Code



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